

PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2676763

SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>HONG SIK KIM</td> <td>12/06/2013</td> </tr> <tr> <td>HYUN JIN YOON</td> <td>12/06/2013</td> </tr> </tbody> </table>		Name	Execution Date	HONG SIK KIM	12/06/2013	HYUN JIN YOON	12/06/2013				
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<table border="1"> <tr> <td>Name:</td> <td>LG ELECTRONICS INC.</td> </tr> <tr> <td>Street Address:</td> <td>20 Yeouido-dong Yeongdeungpo-gu</td> </tr> <tr> <td>City:</td> <td>Seoul</td> </tr> <tr> <td>State/Country:</td> <td>KOREA, REPUBLIC OF</td> </tr> <tr> <td>Postal Code:</td> <td>150-721</td> </tr> </table>		Name:	LG ELECTRONICS INC.	Street Address:	20 Yeouido-dong Yeongdeungpo-gu	City:	Seoul	State/Country:	KOREA, REPUBLIC OF	Postal Code:	150-721
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CORRESPONDENCE DATA											
<p>Fax Number: (202)739-3001</p> <p>Phone: 2027393000</p> <p>Email: adowney@morganlewis.com, patents@morganlewis.com</p> <p><i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i></p> <p>Correspondent Name: COLLIN PARK</p> <p>Address Line 1: 1111 PENNSYLVANIA AVENUE NW</p> <p>Address Line 4: WASHINGTON, DISTRICT OF COLUMBIA 20004</p>											
ATTORNEY DOCKET NUMBER:	001401-7118										
NAME OF SUBMITTER:	ROBERT J. GOODELL										
Signature:	/Robert J. Goodell/										
Date:	01/10/2014										
<p>Total Attachments: 1</p> <p>source=001401-7118_Assignment-01102014#page1.tif</p>											

ATTORNEY DOCKET NO.: 041993-
SOLE/JOINT INVENTION
(U.S. Rights Only)

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

CASE FOR MOBILE PHONES

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on ____, (Application No. ____); and


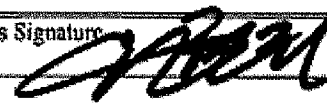
WHEREAS, LG ELECTRONICS INC., a corporation of the Republic of Korea, whose post office address is 20 Yeouido-dong Yeongdeungpo-gu Seoul 150-721 Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parenthesis (Application No. _____, filed _____) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor Hong Sik KIM	Assignor's Signature 	Date December 6, 2013
Address 19, Yangjae-daero 11-gil, Seocho-gu, Seoul, Korea		Citizenship Korean
Full Name of Second Assignor Hyun Jin YOON	Assignor's Signature 	Date December 6, 2013
Address 19, Yangjae-daero 11-gil, Seocho-gu, Seoul, Korea		Citizenship Korean
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		